



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

2815  
#8/B  
Amend B  
Y Robinson  
5/17/03

Applicant: Cheng-Lien Chiang  
Assignee: Bridge Semiconductor Corporation  
Title: OPTOELECTRONIC SEMICONDUCTOR PACKAGE DEVICE  
Serial No.: 10/082,500 Filed: February 25, 2002  
Examiner: Chu, C. Group Art Unit: 2815  
Atty. Docket No.: BDG005-3

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D.C. 20231

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02 FC:1000 756.00 CH

**RESPONSE**

In response to the Office Action dated April 10, 2003, please amend the application as follows.

**In the Specification**

Replace the paragraph at page 3, lines 13-20 with the following paragraph:

Optoelectronic packages for optical sensors often include a chip carrier, an optoelectronic chip mounted in a cavity of the chip carrier, and a transparent window positioned above the chip that hermetically seals the cavity and passes through the incident light to the chip. The optoelectronic chip typically includes a light sensitive cell that comprises an array of tiny photosensor elements, such as charge coupled devices (CCDs) or complimentary metal oxide semiconductor (CMOS) photoreceptors. The photosensor elements convert the light energy incident upon them into electrical signals on an element-by-element or pixel-by-pixel basis. These signals convey information about the intensity, color, hue, saturation and other attributes of the incident light.